



**NGAC TC907-92** is a thermally conductive and electrically insulating adhesive which can be cured at room temperature. It was designed for assembling heat sensitive components onto printed circuit boards. It is recommended for any application requiring strong adhesive bonds and excellent thermal transfer.

**NGAC TC907-92** bonds to a wide range of substrates including metals, glass and plastics. The NGAC TC907-92 has a low coefficient of thermal expansion and will provide excellent resistance to mismatched substrates and very low shrinkage. This adhesive passes NASA outgassing specifications.

Please email [info@nextgenadhesives.com](mailto:info@nextgenadhesives.com) or call (978) 436-9600 for a FREE SAMPLE.